

## **Glass Passivated Bridge Rectifier**

Voltage 1000 V Current 25A

### **Features**

- UL recognition file number E228882
- Ideal for printed circuit boards
- Lead free in compliance with EU RoHS 2.0
- Green molding compound as per IEC 61249 standard

### **Mechanical Data**

• Case: GBJ-1 Package

• Terminals : Solderable per MIL-STD-750, Method 2026

• Approx. Weight: 0.2395 ounces, 6.79 grams

### **Application**

- Desktop/Workstation 80+ Silver & Gold Standard,
- Server Power Supply 90+ Platinum & Titanium Standard
- Home Appliances Air Con
- Telecom Power Supply Networking station, data center SMPS
- Industrial Power Supply Street Lighting, Synergy Panels





# **Maximum Ratings and Thermal Characteristics** ( $T_A = 25$ °C unless otherwise noted)

PARAMETER	SYMBOL	LIMIT	UNITS	
Maximum Repetitive Peak Reverse Voltage		$V_{RRM}$	1000	V
Maximum RMS Voltage	$V_{RMS}$	700	V	
Maximum DC Blocking Voltage	V <sub>DC</sub>	1000	V	
Maximum Average Forward Current		I <sub>F(AV)</sub>	25	Α
Peak Forward Surge Current: 8.3 ms Single Half Sine-Wave Superimposed On Rated Load	@ T <sub>A</sub> = 25 °C @ T <sub>A</sub> = 125 °C	IFSM	300 240	Α
Peak Forward Surge Current: 1.0 ms Single Half Sine-Wave Superimposed On Rated Load	@ T <sub>A</sub> = 25 °C @ T <sub>A</sub> = 125 °C	I <sub>FSM</sub>	600 480	А
I <sup>2</sup> t rating for fusing (t = 8.3ms)	I²t	374	A <sup>2</sup> S	
Typical Junction Capacitance Measured at 1 MHZ And Applied $V_R = 4 \text{ V}$	Сл	120	pF	
Typical Thermal Resistance (Note 2)		Rejc	1.1	°C/W
Operating Junction Temperature Range	TJ	-55~150	°C	
Storage Temperature Range		Tstg	-55~150	°C

## **Electrical Characteristics** (T<sub>A</sub> = 25 °C unless otherwise noted)

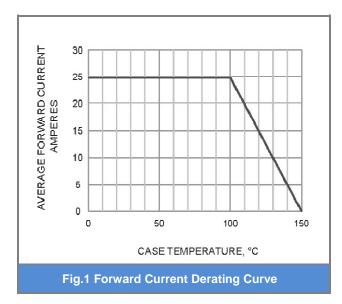
PARAMETER	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNITS	
Forward Voltage	V <sub>F</sub>	I <sub>F</sub> = 12.5 A, T <sub>J</sub> = 25 °C	ı	-	1.0	V	
Reverse Current	I <sub>R</sub>	V <sub>R</sub> = 1000 V, T <sub>J</sub> = 25 °C	-	-	5	uA	
		V <sub>R</sub> = 1000 V,T <sub>J</sub> = 125 °C	-	-	500		

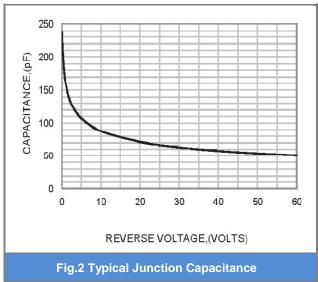
#### NOTES:

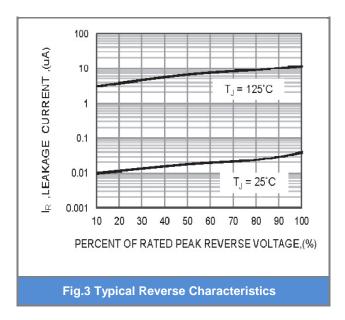
- 1. Mounted on a FR4 PCB standard pad
- 2. Device mounted on 150mm\*150mm\*1.6mm Cu Plate Heatsink.

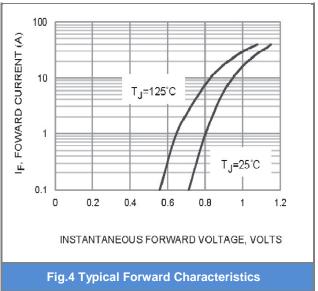


### **TYPICAL CHARACTERISTIC CURVES**







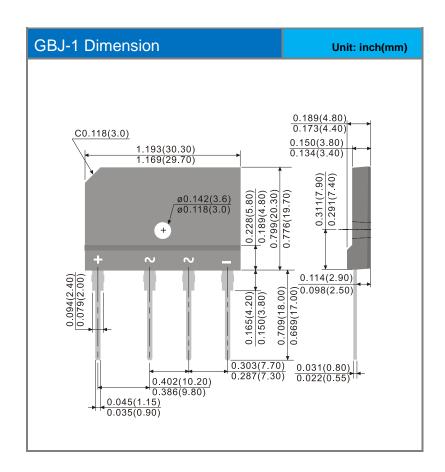




## Part No. Packing Code Version

Part No. Packing Code	Package Type	Packing Type	Marking
GBJ25MI_B0_00101	GBJ-1	200 pcs / Box	GBJ25MI

## **Packaging Information**





### Disclaimer

- Reproducing and modifying information of the document is prohibited without permission from Panjit International Inc..
- Panjit International Inc. reserves the rights to make changes of the content herein the document anytime without notification. Please refer to our website for the latest document.
- Panjit International Inc. disclaims any and all liability arising out of the application or use of any product including damages incidentally and consequentially occurred.
- Panjit International Inc. does not assume any and all implied warranties, including warranties of fitness for particular purpose, non-infringement and merchantability.
- Applications shown on the herein document are examples of standard use and operation. Customers are
  responsible in comprehending the suitable use in particular applications. Panjit International Inc. makes no
  representation or warranty that such applications will be suitable for the specified use without further testing or
  modification.
- The products shown herein are not designed and authorized for equipments requiring high level of reliability or relating to human life and for any applications concerning life-saving or life-sustaining, such as medical instruments, transportation equipment, aerospace machinery et cetera. Customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Panjit International Inc. for any damages resulting from such improper use or sale.
- Since Panjit uses lot number as the tracking base, please provide the lot number for tracking when complaining.